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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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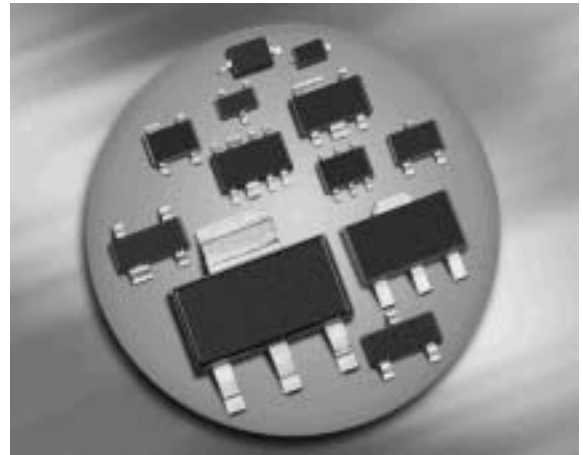
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



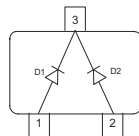
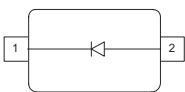
### Silicon Tuning Diode

- Excellent linearity
- High Q hyperabrupt tuning diode
- Low series resistance
- High capacitance ratio
- Designed for low tuning voltage operation for VCO's in mobile communications equipment
- For control elements such as TCXOs and VCXOs
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



**BBY57-02L**  
**BBY57-02V**  
**BBY57-02W**

**BBY57-05W**



Type	Package	Configuration	$L_S$ (nH)	Marking
BBY57-02L	TSLP-2	single	0.4	55
BBY57-02V	SC79	single	0.6	5
BBY57-02W	SCD80	single	0.6	55
BBY57-05W	SOT323	common cathode	1.4	D5s

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	10	V
Forward current	$I_F$	20	mA
Operating temperature range	$T_{op}$	-55 ... 125	°C
Storage temperature	$T_{stg}$	-55 ... 150	

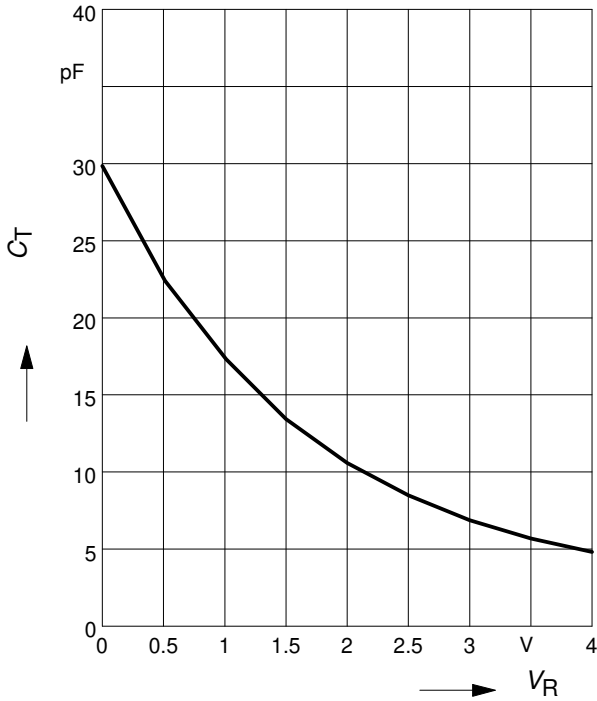
<sup>1)</sup>Pb-containing package may be available upon special request

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Reverse current	$I_R$				nA
$V_R = 8\text{ V}$		-	-	10	
$V_R = 8\text{ V}, T_A = 85^\circ\text{C}$		-	-	100	
<b>AC Characteristics</b>					
Diode capacitance	$C_T$				pF
$V_R = 1\text{ V}, f = 1\text{ MHz}$		16.5	17.5	18.6	
$V_R = 2.5\text{ V}, f = 1\text{ MHz}$		-	9.35	-	
$V_R = 3\text{ V}, f = 1\text{ MHz}$		-	7	-	
$V_R = 4\text{ V}, f = 1\text{ MHz}$		4	4.7	5.5	
Capacitance ratio	$C_{T1}/C_{T3}$	-	2.45	-	
$V_R = 1\text{ V}, V_R = 3\text{ V}, f = 1\text{ MHz}$					
Capacitance ratio	$C_{T1}/C_{T4}$	3	3.7	4.5	
$V_R = 1\text{ V}, V_R = 4\text{ V}, f = 1\text{ MHz}$					
Series resistance	$r_S$				$\Omega$
$V_R = 1\text{ V}, f = 470\text{ MHz}, \text{BBY57-02L}$		-	0.35	-	
$V_R = 1\text{ V}, f = 470\text{ MHz}, \text{all others}$		-	0.3	-	

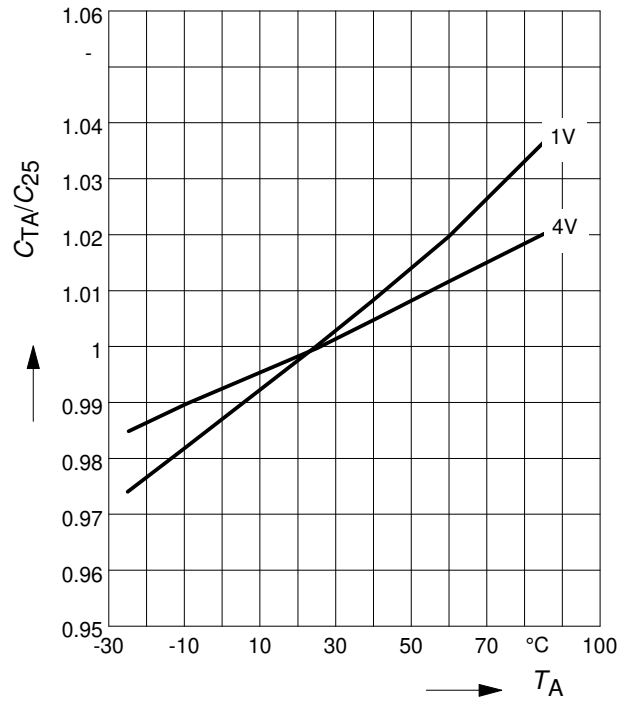
**Diode capacitance  $C_T = f(V_R)$**

$f = 1\text{MHz}$

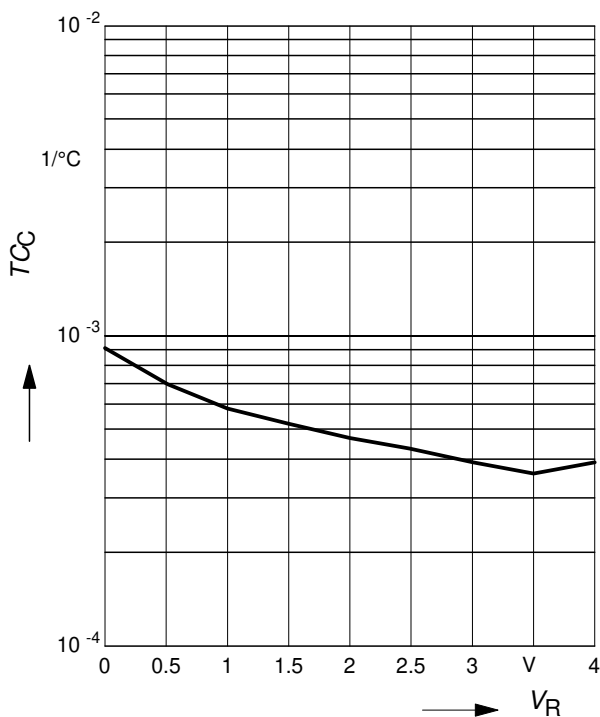


**Normalized diode capacitance**

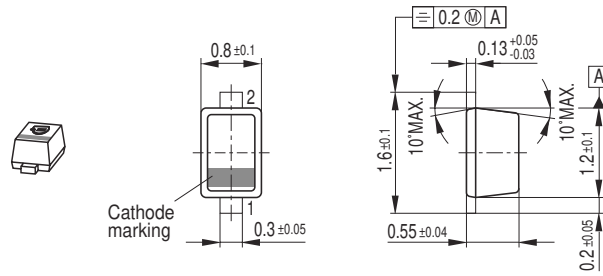
$C_{(T_A)}/C_{(25^\circ\text{C})} = f(T_A); f = 1\text{MHz}$



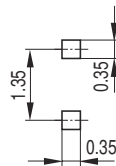
**Temperature coefficient of the diode capacitance  $T_{CC} = f(V_R)$**



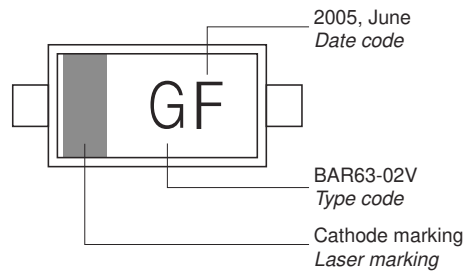
Package Outline



Foot Print

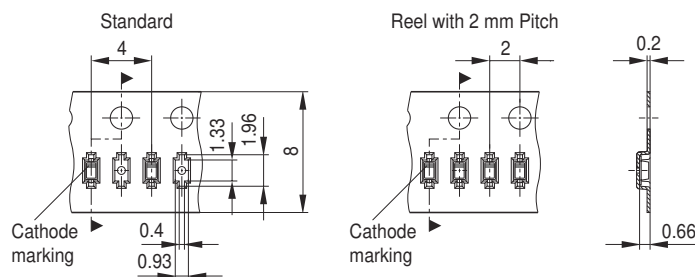


Marking Layout (Example)

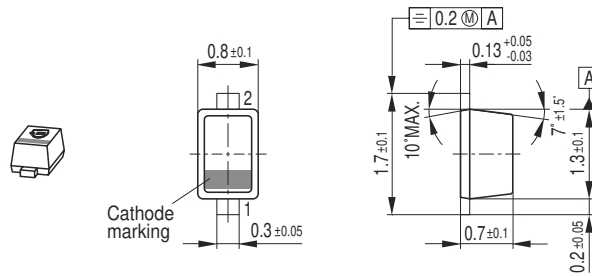


Standard Packing

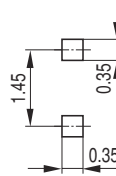
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 180 mm = 8.000 Pieces/Reel (2 mm Pitch)  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



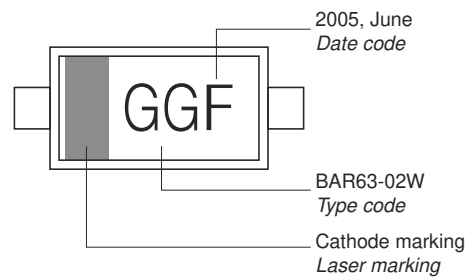
Package Outline



Foot Print

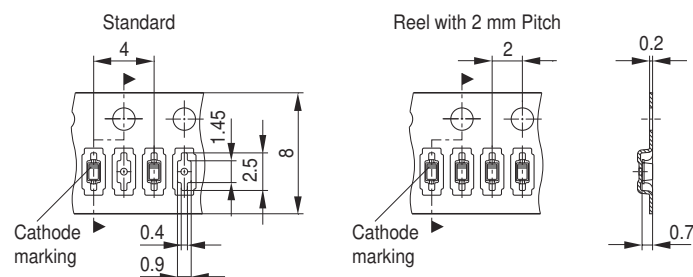


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 180 mm = 8.000 Pieces/Reel (2 mm Pitch)  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

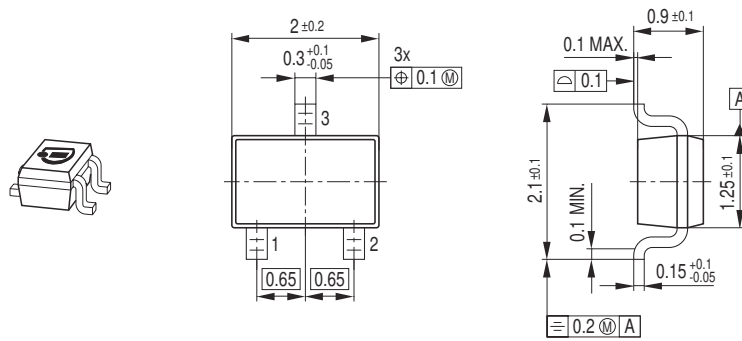


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

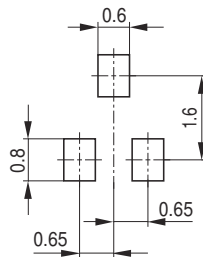
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

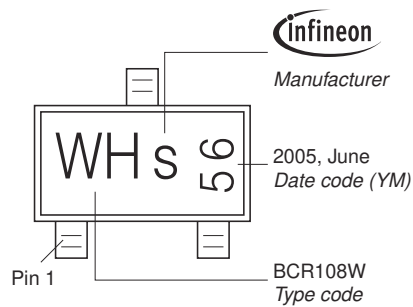
Package Outline



Foot Print

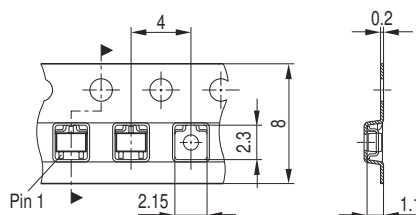


Marking Layout (Example)



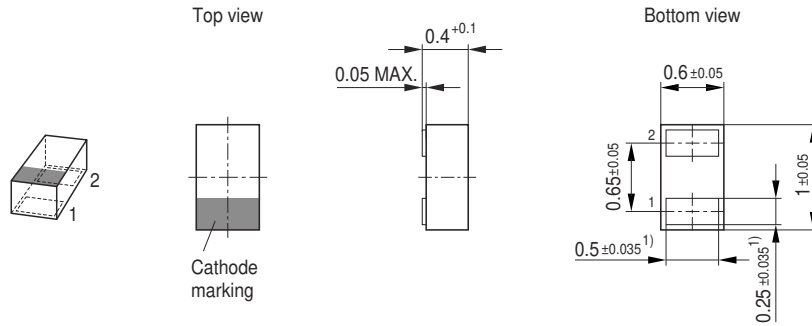
Standard Packing

Reel  $\varnothing 180$  mm = 3.000 Pieces/Reel  
 Reel  $\varnothing 330$  mm = 10.000 Pieces/Reel





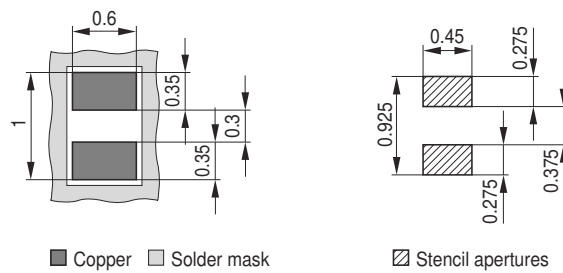
### Package Outline



1) Dimension applies to plated terminal

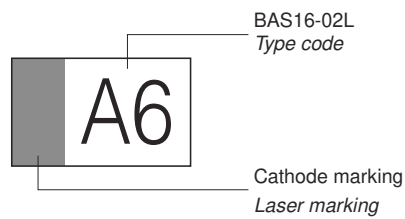
### Foot Print

For board assembly information please refer to Infineon website "Packages"



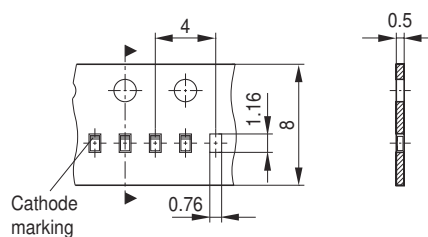
■ Copper    □ Solder mask    ▨ Stencil apertures

### Marking Layout (Example)



### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel  
 Reel ø330 mm = 50.000 Pieces/Reel (optional)



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